Packaging Piece, Based on Framework and Adopting Bonding Wire Connecting Technology, and Manufacturing Technology Thereof

Abstract

The invention discloses a packaging piece, based on a framework and adopting the bonding wire connecting technology, and the manufacturing technology of the packaging piece. The packaging piece comprises chips, a plastic package body, silver coatings and bonding wires. The silver coatings are mutually independent silver coating sections, and the chips are arranged on part of the silver coatings. The chips and part of the silver coatings without the chips are connected through the bonding wires. The plastic package body encircles the chips, the silver coatings and the bonding wires, and the chips, the silver coatings and the bonding wires form a power supply of a circuit and signal paths. The packaging piece further comprises metal protruding points. The manufacturing technology includes the steps of framework silvering, wafer thinning, scribing, arrangement of the chips, metal protruding point forming, bonding, plastic package, framework corrosion, incision and packaging. The step of forming the metal protruding points can be omitted. The design of a framework graphic is completed in the period of manufacturing the framework due to the fact that bonding is directly conducted on the formed metal protruding points after electrosilvering or wire bond is directly conducted after the electrosilvering. Manufacturing cycle is shortened. Interconnection of the chips and supports is preferably achieved. I/ O is more intensive. Cost is lower.

Fig. 6